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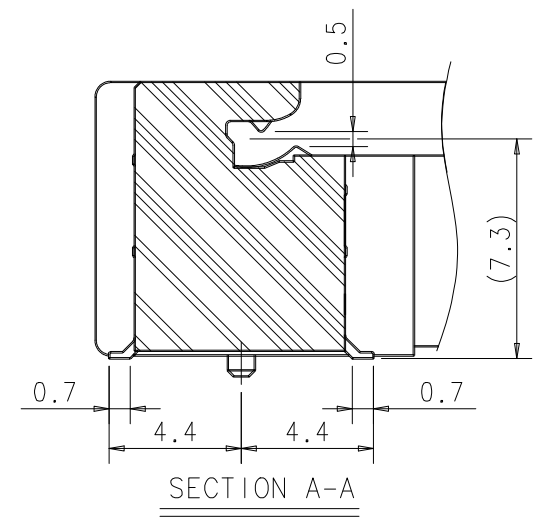
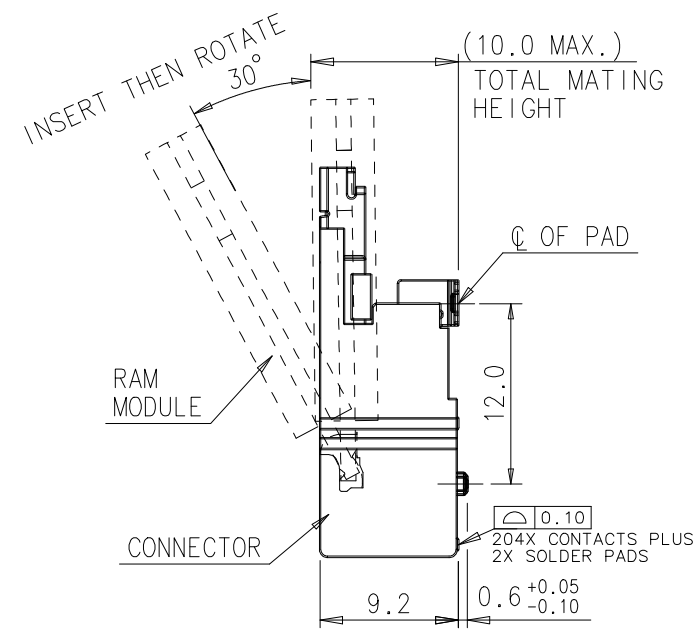
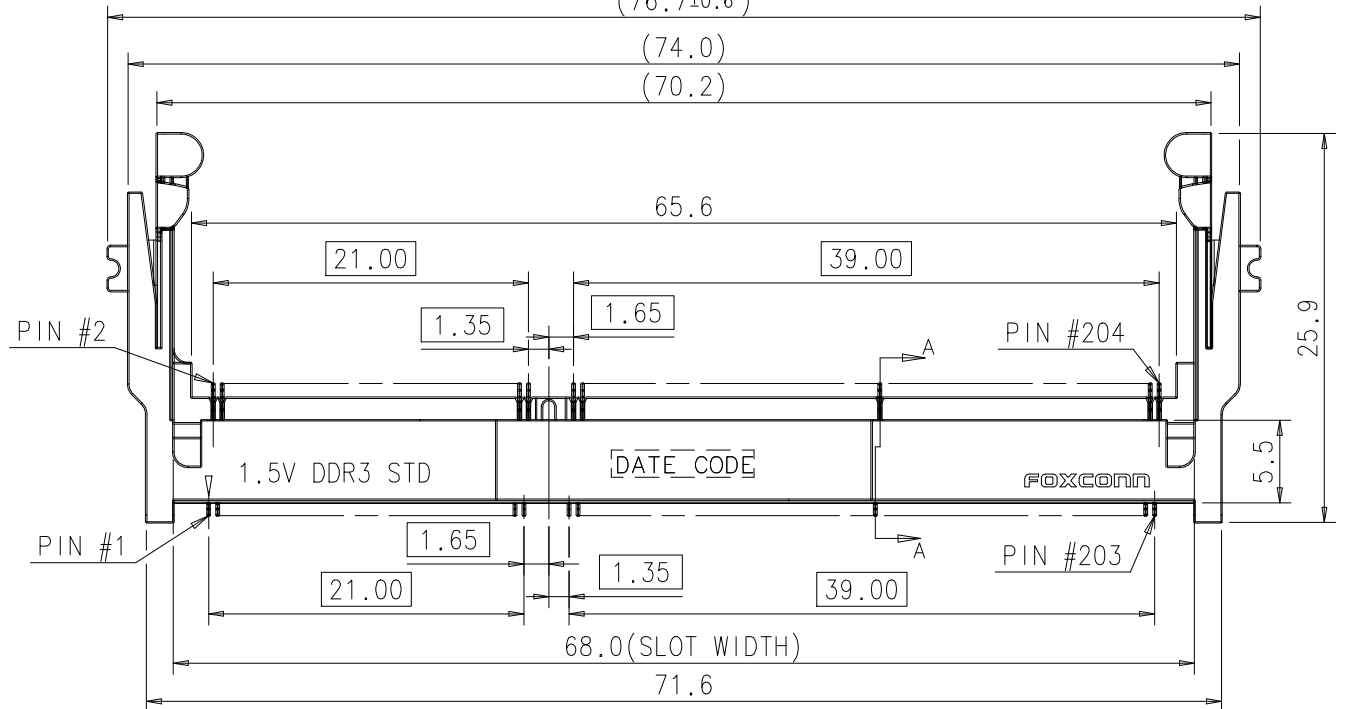
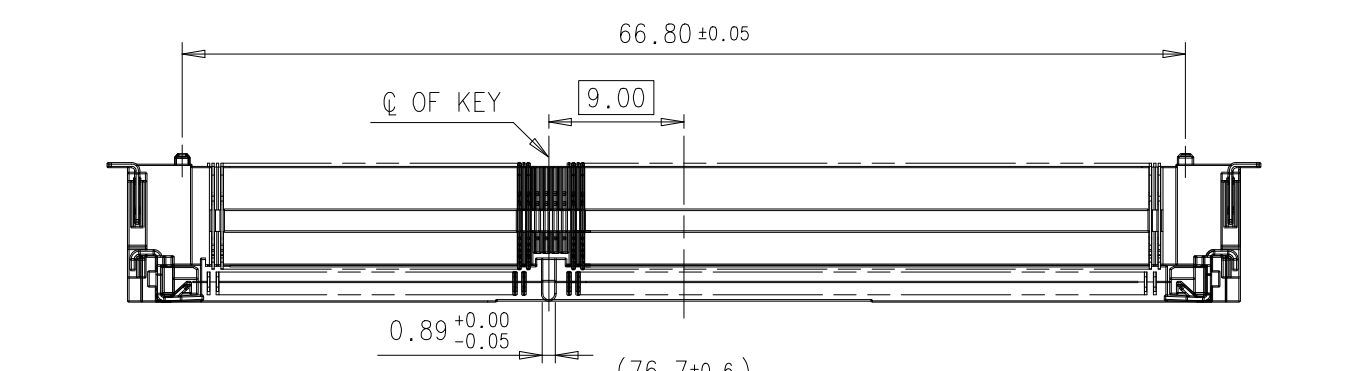
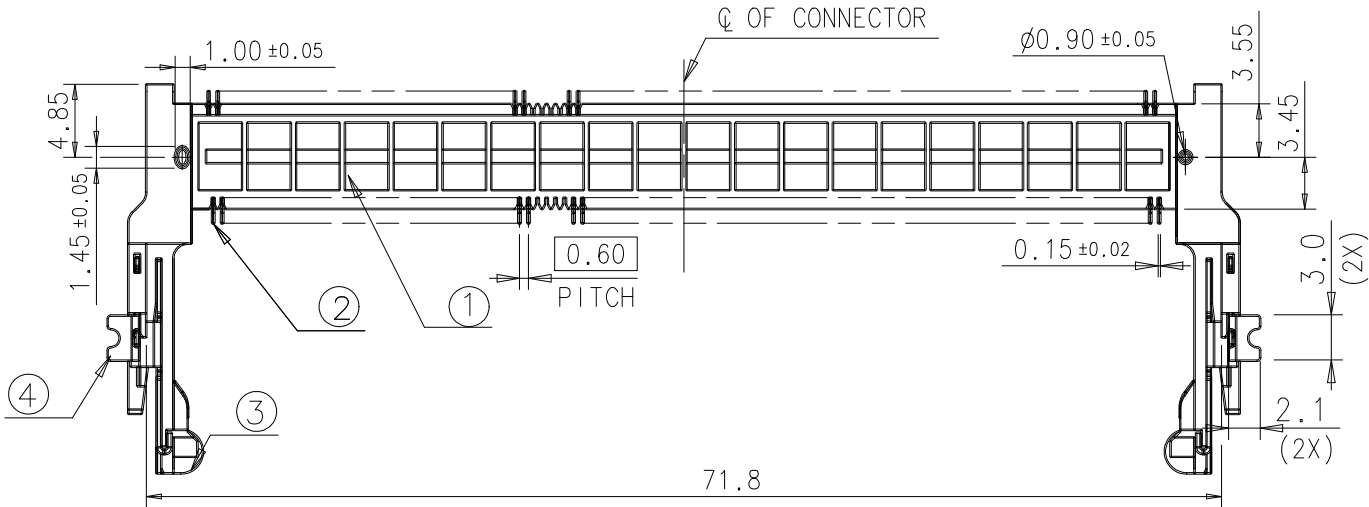
E	BC-13-0001319	C.S Li	REV.	ECN. NO.	APPD.
F	BC-13-0087023	C.S Li	A	BC-10-0052206	Herry Yang
G	BC-15-0001270	C.S Li	B	BC-10-0075105	Herry Yang
			C	BC-11-0028404	Herry Yang
			D	BC-11-0119660	Herry Yang

NOTES:

- ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
(PER PIN) DOESN'T EXCEED 30°C ABOVE AMBIENT AT 0.5 AMPERE MAX. PER PIN.
 - VOLTAGE RATING: 25V AC.
 - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
 - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
 - CONTACT RESISTANCE: 50 MILLIOHMS MAX. PER PIN INITIAL.
60 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENTAL TESTING.
- MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
- OPERATION TEMPERATURE: -55°C TO +85°C.
- RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260°C, 10~20S.
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAIL & AVAILABILITY.

PART NO. DESCRIPTION: A S O A6 2 * - H A S N - * H

- MEMORY MODULE SOCKET
- HORIZONTAL TYPE
- SINGLE ROW
- NO. OF POS. A6 = 204 POS.
- SMT
- CONTACT AREA PLATING
 - 1=GOLD FLASH
 - Y=5u" GOLD PLATING
 - 6=10u" GOLD PLATING
 - 7=15u" GOLD PLATING
 - 3=30u" GOLD PLATING
- H=HALOGEN/LEAD FREE
- 4=SOFT TRAY
- 7=TAPE REEL
- N=GENERAL TYPE
- S=STANDARD
- A=9.2mm HEIGHT
- DDR CONNECTOR



ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
④	METAL PAD	2	COPPER ALLOY	50u" NICKEL UNDER PLATING OVER ALL 2u" Pd PLATING OVER SOLDER AREA
③	METAL SPRING	2	COPPER ALLOY	50u" NICKEL PLATING OVER ALL
②	CONTACT	204	COPPER ALLOY	50u" NICKEL UNDER PLATING GOLD FLASH AT TAIL GOLD FLASH OR 5u" OR 10u" OR 15u" OR 30u" GOLD PLATING AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN-FREE, IVORY COLOR

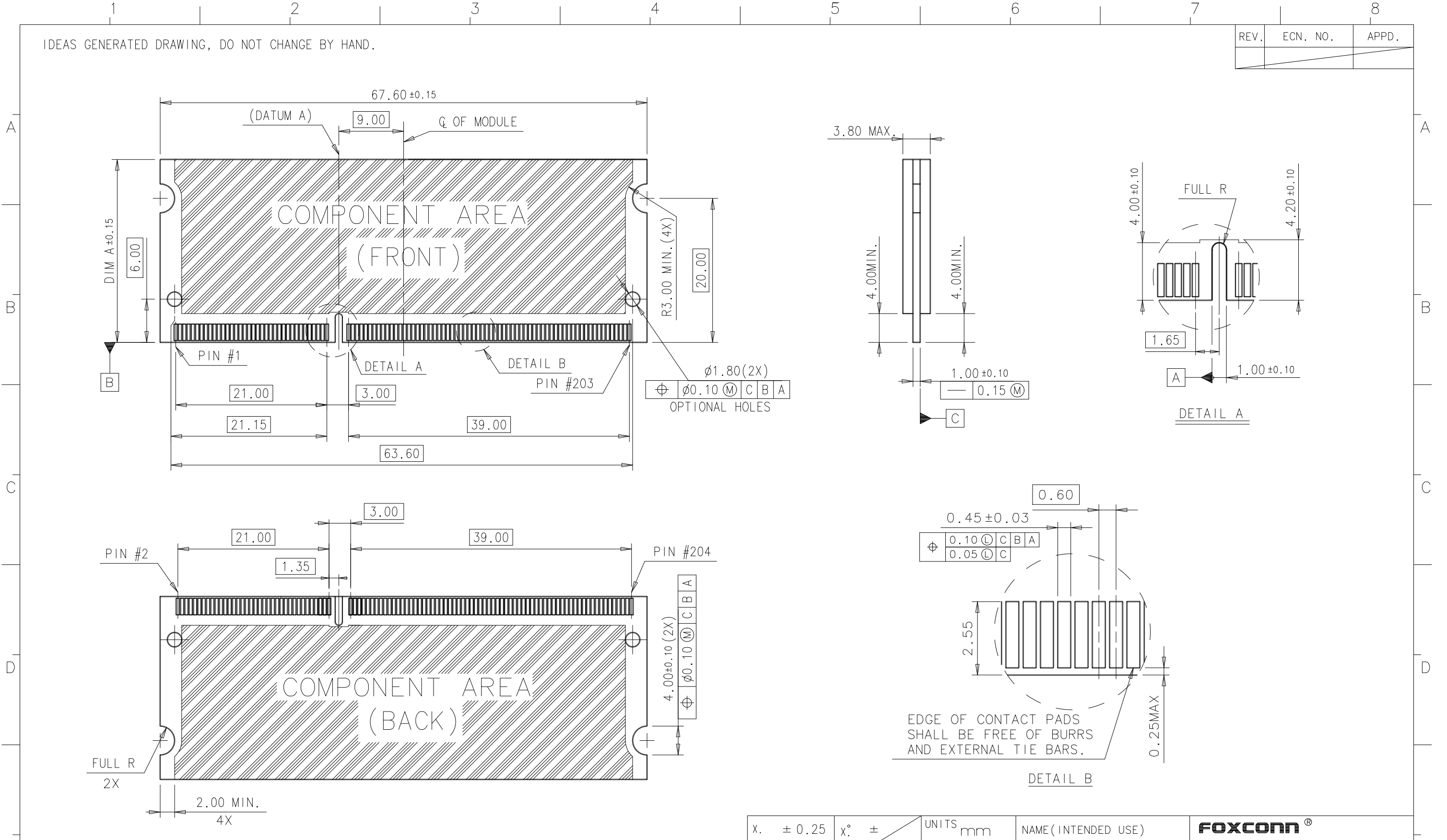
X.	± 0.30	X°	±	UNITS	mm
.X	± 0.25	.X°	±	MAT'L	
.XX	± 0.15	.XX°	±	FINISH	
.XXX	±	.XXX°	±	Q'TY	

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NAME (INTENDED USE)	DDR III SO DIMM CONNECTOR	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED
PART NO. (INTENDED USE)	ASOA62*-HASN-*H	
APPD:	C.S Li	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
CHKD:	ZH Wang	TITLE: CUSTOMER DRAWING
DR:	Wang Justin 1/7'15	DWG NO.: 317-0000-1906
		SCALE SHEET REV. N/A 1/5 G

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REV.	ECN. NO.	APPD.



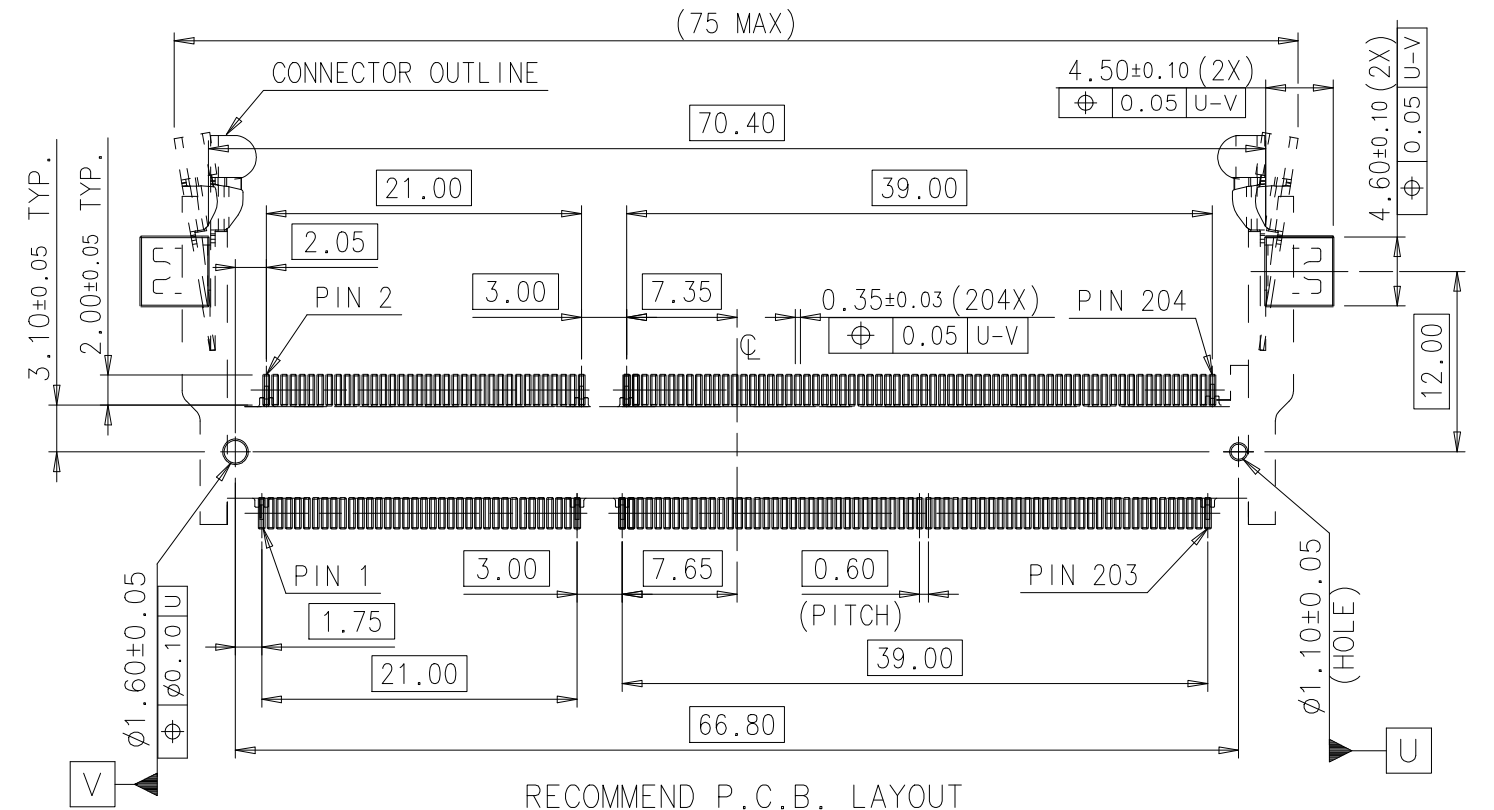
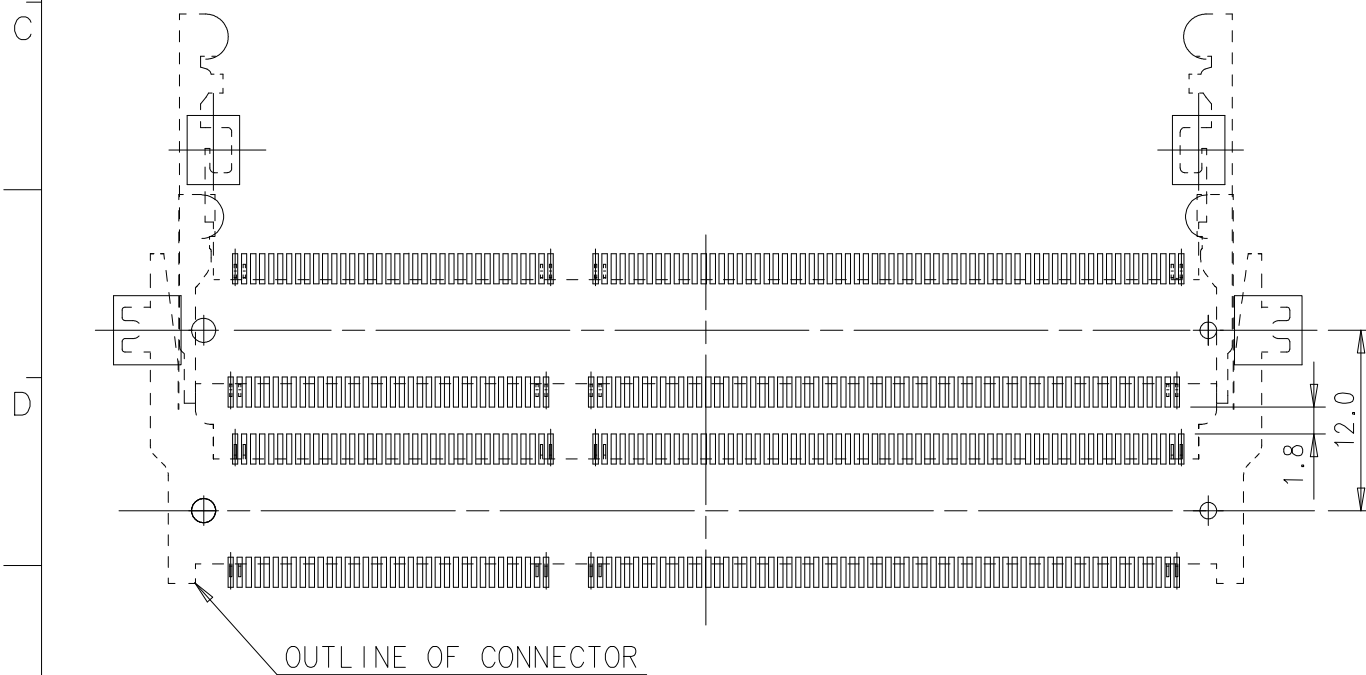
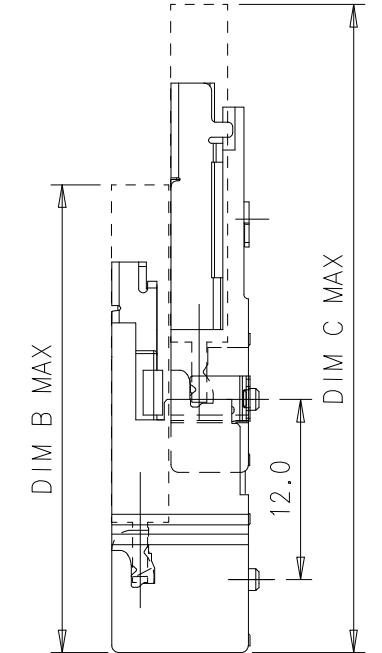
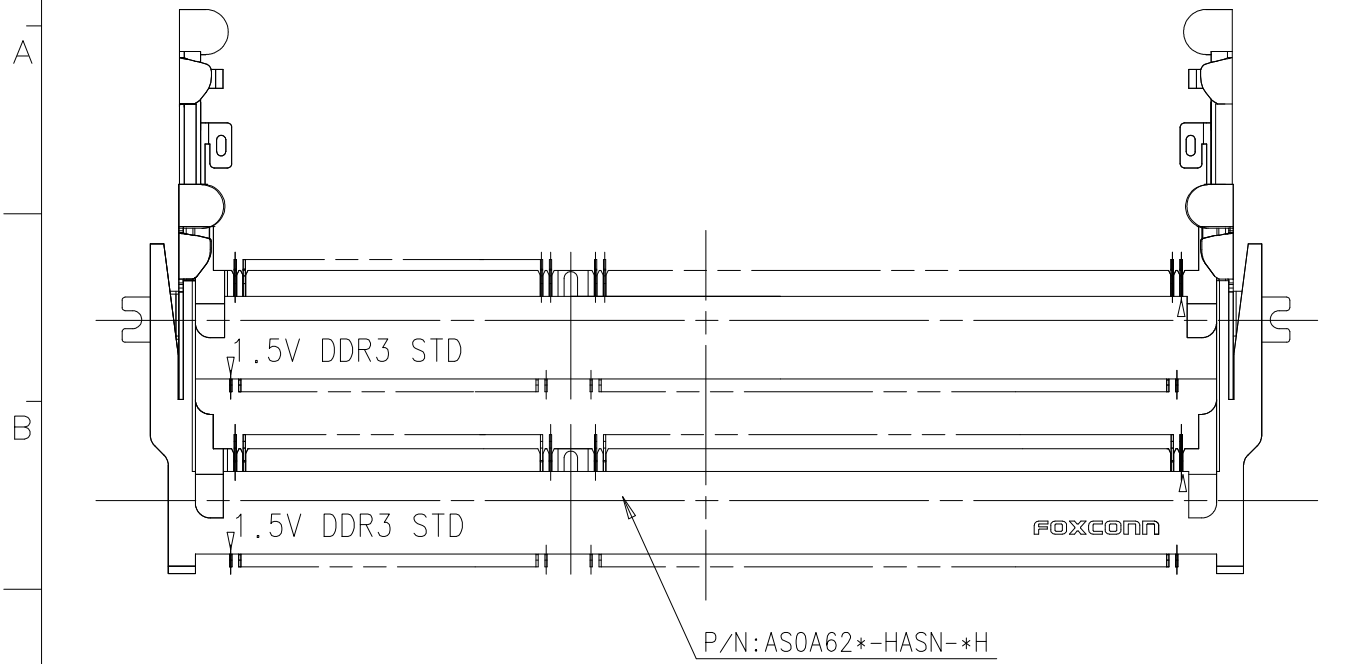
DDR III SO-DIMM MODULE BOARD LAYOUT

SDRAM VARIATIONS	DIM A
TYPE 1	25.40
TYPE 2	31.75
TYPE 3	30.00

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED
.X ± 0.10	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	
.XX ± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		ASOA62*-HASN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1906
			DR: Wang Justin 1/7'15	SCALE SHEET REV. N/A 2/5 G

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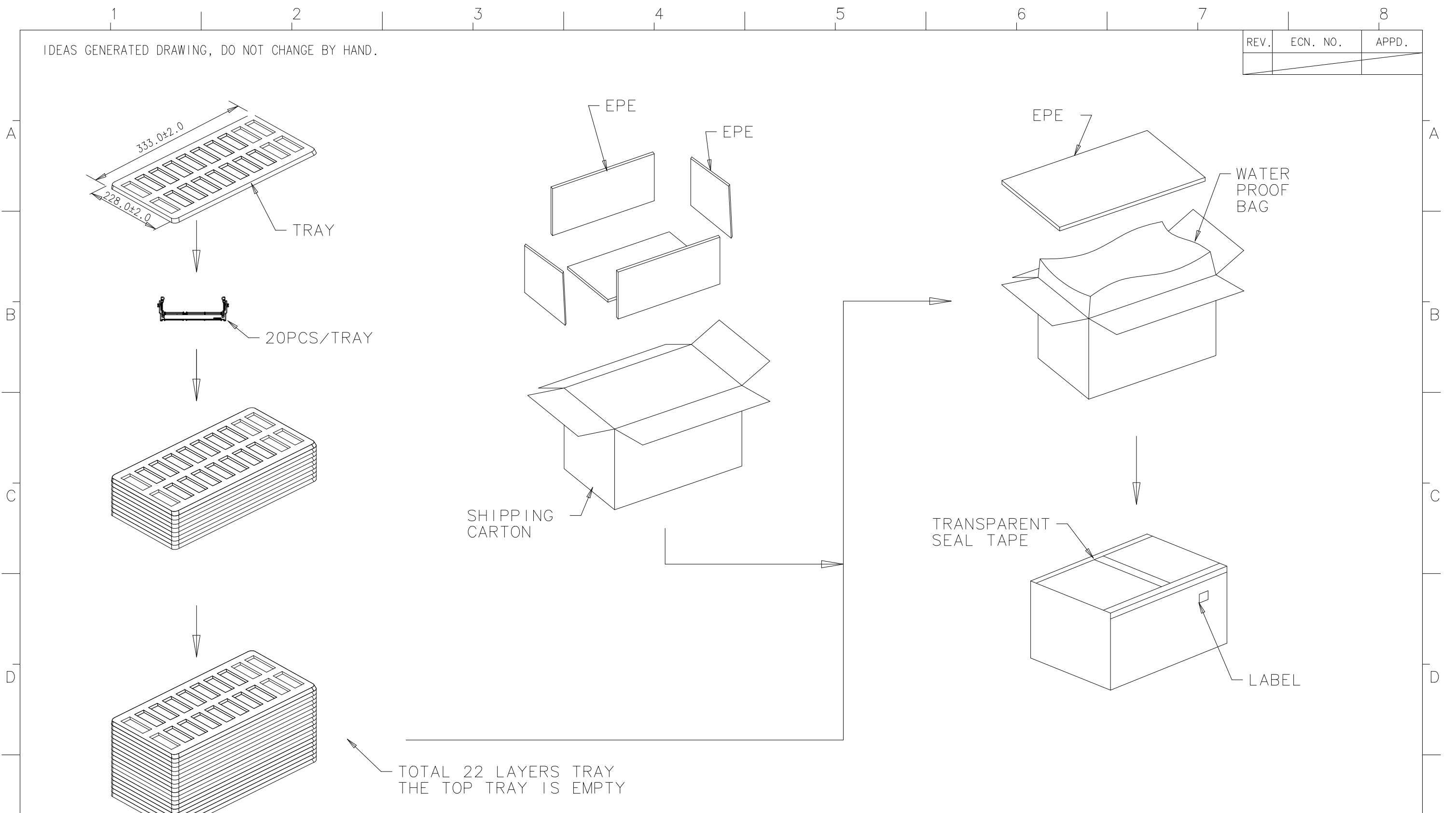
P.C.B. LAYOUT (STACKED ORIENTATION)

SDRAM VARIATIONS	DIM B	DIM C
TYPE 1	30.4	42.4
TYPE 2	36.7	48.7
TYPE 3	35.0	47.0

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED
.X ± 0.10	.X° ±		DDR III SO DIMM CONNECTOR	
.XX ± 0.05	.XX° ±	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		AS0A62*-HASN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1906
Q'TY			DR: Wang Justin 1/7'15	SCALE SHEET REV. N/A 3/5 G

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REV.	ECN. NO.	APPD.



NOTES:

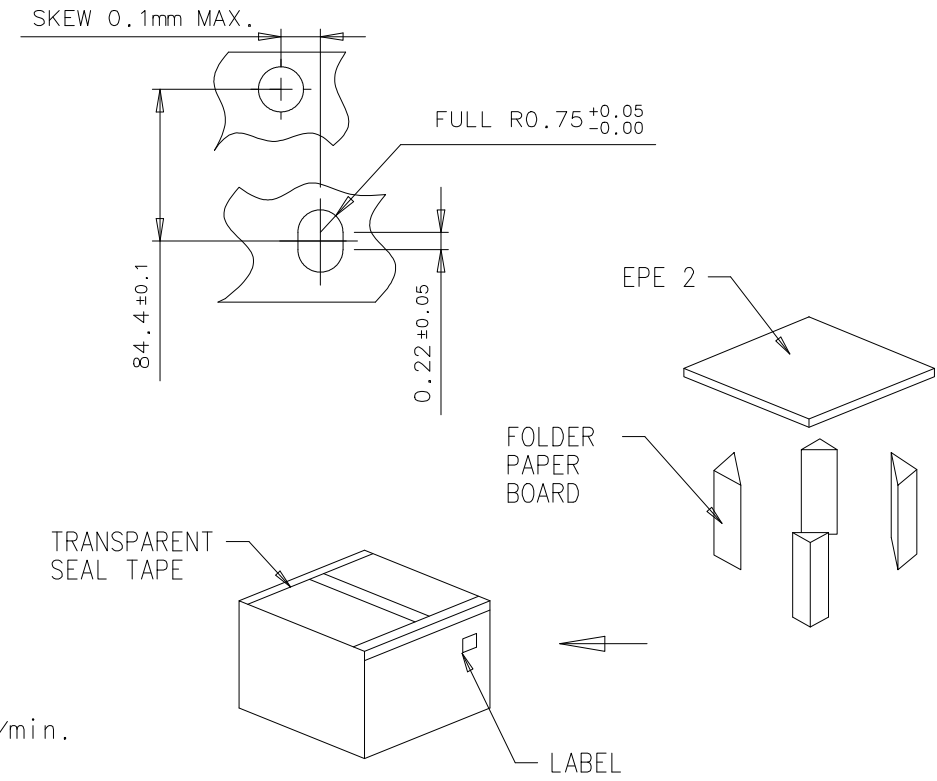
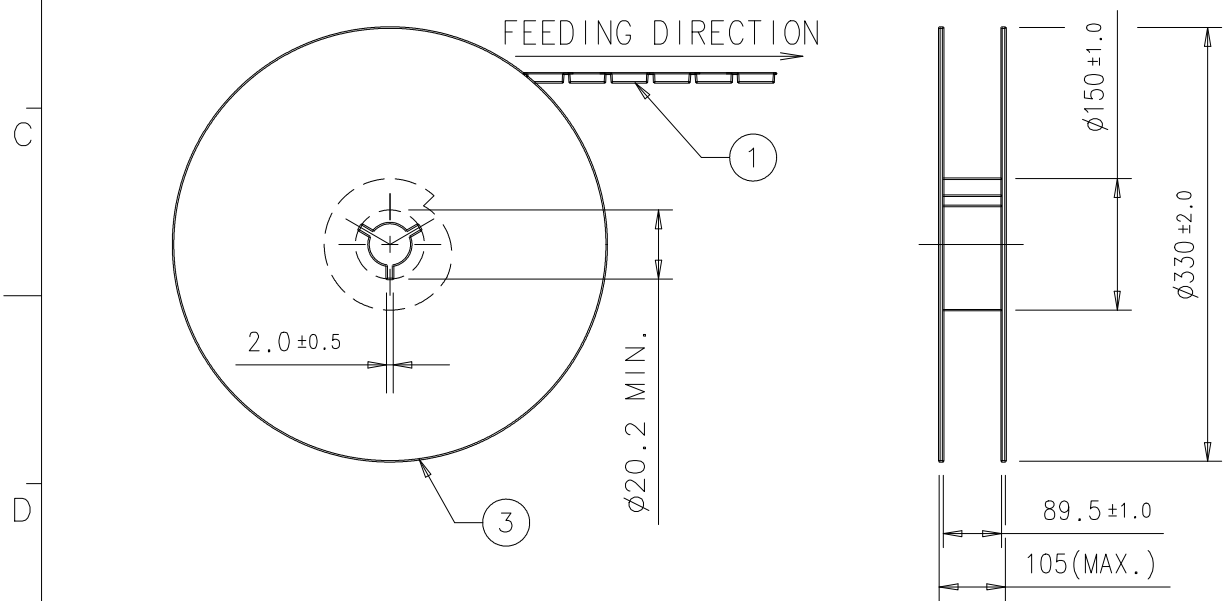
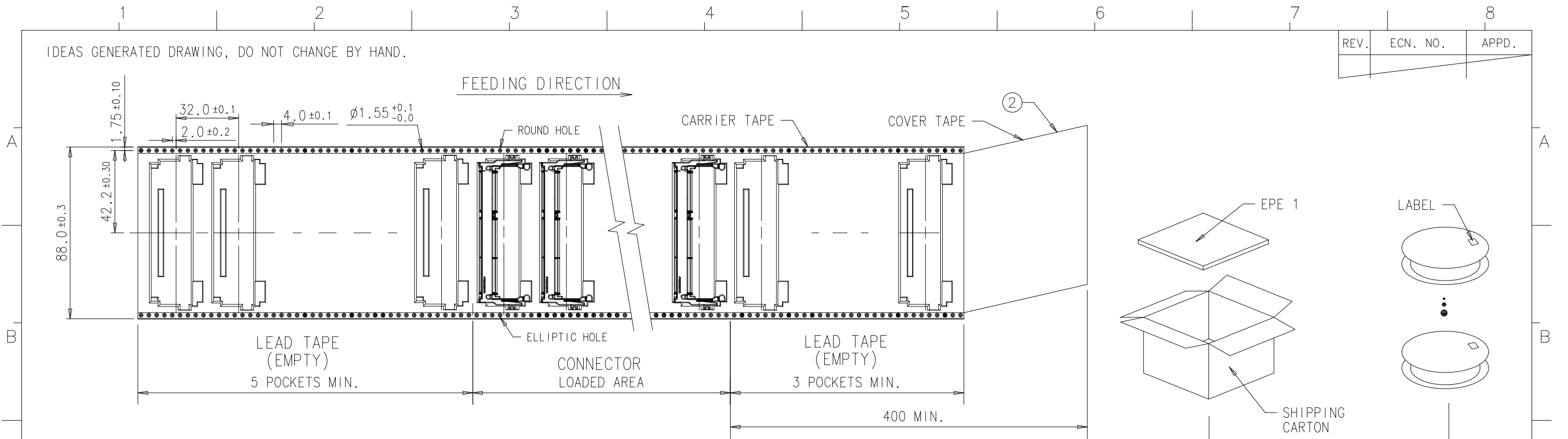
1. PACKING CAPACITY : 20 PCS/TRAY, 21 TRAYS/BOX,
TOTAL 420 PCS/BOX.

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN [®] FOXCONN INTERCONNECT TECHNOLOGY LIMITED
.X ± 1.0	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	
.XX ± 0.2	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		AS0A62*-HASN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1906
Q'TY			DR: Wang Justin 1/7'15	SCALE SHEET REV.
				N/A 4/5 G

CONNECTOR P/N AS0A62*-HASN-4H

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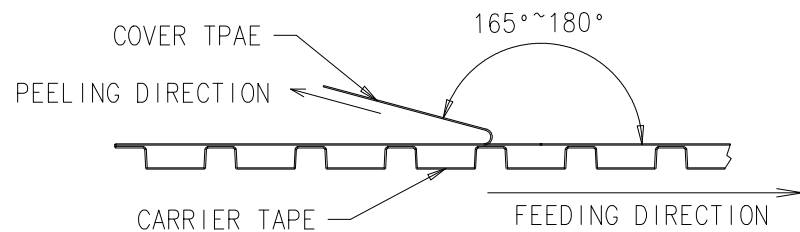
REV.	ECN. NO.	APPD.



ITEM	DESCRIPTION	MATERIAL
③	REEL	POLYSTYRENE
②	COVER TAPE	POLYESTER
①	CARRIER TAPE	POLYSTYRENE

NOTES:

- 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE $\pm 0.20\text{mm}$.
- COVER TAPE PEELING STRENGTH : 0.01kgf MIN., 0.15 kgf MAX. AT 300mm/min.



- PACKING CAPACITY : 110 PCS/REEL, 3 REELS/BOX, TOTAL 330 PCS/BOX.

CONNECTOR P/N AS0A62*-HASN-7H

X. ± 1.5	X° \pm	UNITS mm	NAME (INTENDED USE)
.X ± 1.0	.X° \pm	MAT'L	DDR III SO DIMM CONNECTOR
.XX ± 0.2	.XX° \pm	FINISH	PART NO. (INTENDED USE)
.XXX \pm	.XXX° \pm	Q'TY	AS0A62*-HASN-*H
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			CHKD: ZH Wang
			DR: Wang Justin 1/7'15

FOXCONN®		
FOXCONN INTERCONNECT TECHNOLOGY LIMITED.		
CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL		
TITLE: CUSTOMER DRAWING		
DWG NO.: 317-0000-1906		
SCALE	SHEET	REV.
N/A	5/5	G

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